# MN3111H

Vertical Driver LSI for Video Camera CCD Area Image Sensor

# Overview

The MN3111H is a vertical driver LSI for a two-dimensional interline CCD image sensor. It features a built-in power supply circuit that, in conjunction with such external components as four booster capacitors, six voltage stabilization capacitors, eight Schottky barrier diodes, and two Zener diodes, produces stabilized +15.0V and -10.0V power supplies from a +5.0V input and HD pulses.

#### Features

• Single 5 volt power supply

#### Applications

Video cameras

### Pin Assignment



### Block Diagram



# Pin Descriptions

Pin No.	Symbol	Pin Name	I/O	Function Description		
9	V <sub>CC1</sub>	"H" level power supply	Ι	"H" level input for 5 volt circuits		
23	V <sub>CC2</sub>	for input block				
3	GND	"L" level power supply	Ι	"L" level input for 5 volt circuits		
45		for input block				
25	$V_{\rm H}$	"H" level power supply	Ι	"H" level input for high-voltage circuits		
		for vertical driver				
35	$V_{\rm HH}$	"H" level power supply	Ι	"H" level input for high-voltage circuits		
		for SUB driver				
30	V <sub>M13</sub>	"M" level power supply	Ι	"M" level input for high-voltage circuits		
27	V <sub>M24</sub>	for vertical driver				
32	$V_{L1}$	"L" level power supply	Ι	"L" level input for high-voltage circuits		
		for vertical driver				
33	$V_{L2}$	"L" level power supply	Ι	"L" level input for high-voltage circuits		
		for SUB driver				
24	V <sub>DD</sub>	Driver power supply 1	Ι	"H" level for high-voltage circuits		
36	$V_{EE}$	Driver power supply 2	Ι	"L" level for high-voltage circuits		
17	$V_{IN^+}$	Voltage input for positive	Ι	Voltage input pin for positive voltage		
		voltage monitor		monitor		
44	V <sub>IN -</sub>	Voltage input for negative	Ι	Voltage input pin for negative voltage		
		voltage monitor		monitor		
13	TEST	Test input	Ι	Test pin (Keep this pin at "H" level.)		
12	HD	HD pulse input	Ι	HD pulse input pin		
22	IV2	Transfer pulse input	Ι	Charge transfer pulse input pin		
21	IV4	Transfer pulse input	Ι	Charge transfer pulse input pin		
39	IV1	Transfer pulse input	Ι	Charge transfer pulse input pin		
40	IV3	Transfer pulse input	Ι	Charge transfer pulse input pin		
38	CH1	Charge pulse input	Ι	Charge readout pulse input pin		
41	CH2	Charge pulse input	Ι	Charge readout pulse input pin		
37	ISUB	SUB pulse input	Ι	Unwanted charge rejection pulse input pin		
20	SENSE1	Positive voltage monitor	Ι	Positive voltage monitor control sensing		
		sensing input		pin (Leave this pin open.)		
42	SENSE2	Negative voltage monitor	Ι	Negative voltage monitor control sensing		
		sensing input		pin (Leave this pin open.)		
7	C1+	C1 connection	0	Booster block voltage charging capacitor		
8	C1-			connection pins		
6	C2+	C2 connection	0	Booster block voltage charging capacitor		
4	C2-			connection pins		
2	C3+	C3 connection	0	Booster block voltage charging capacitor		
5	C3 –			connection pins		
10	C4+	C4 connection	0	Booster block voltage charging capacitor		
48	C4 –			connection pins		

# ■ Pin Descriptions (continued)

Pin No.	Symbol	Pin Name	I/O	Function Description
11	OV <sub>DD</sub>	Booster block positive	0	Booster block positive voltage
		voltage output		output pin
1	OV <sub>EE</sub>	Booster block negative	0	Booster block negative voltage
		voltage output		output pin
19	V <sub>OUT+</sub>	Positive regulated voltage	0	Positive voltage monitor output pin
		output		(Leave this pin open.)
43	V <sub>OUT-</sub>	Negative regulated voltage	0	Negative voltage monitor output pin
		output		(Leave this pin open.)
26	OV4	Binary transfer pulse	0	Binary $(V_{M24}, V_{L1})$ transfer pulse
		output		output pin
28	OV2	Binary transfer pulse	0	Binary $(V_{M24}, V_{L1})$ transfer pulse
		output		output pin
29	OV3	Tristate transfer pulse	0	Tristate ( $V_H$ , $V_{M13}$ , $V_{L1}$ ) transfer pulse
		output		output pin
31	OV1	Tristate transfer pulse	0	Tristate $(V_H, V_{M13}, V_{L1})$ transfer pulse
		output		output pin
34	OSUB	SUB pulse output	0	Unwanted charge $(V_{HH}, V_{L2})$ rejection
				pulse input pin
14	CAP1	Stabilizing capacitor	0	Pins for connecting capacitors for interna
15	CAP2	connection		voltage stabilization circuits
16	CAP3			
18	N.C.	No connection		
46				
47				

# Functional Description

Binary transfer pulses (vertical driver block)

	,
IV2	OV2
IV4	OV4
Н	L
L	М

# Tristate transfer pulses (vertical driver block)

OV1
OV3
L
М
L
Н

\*1 IV1, IV2, IV3, IV4, CH1, CH2

OV1, OV2, OV3, OV4 H:  $V_H$ M:  $V_{M13}$ , or  $V_{M24}$ L:  $V_{L1}$ 

### Unwanted charge rejection pulses (SUB driver block)

0, 1	(
ISUB	OSUB
Н	L
L	Н
*1 ISUB	
H: V <sub>CC</sub>	
L: GND	
OSUB	
H: V <sub>HH</sub>	
L: V <sub>L2</sub>	

H: V<sub>CC</sub> L: GND

### Electrical Characteristics

#### (1) DC characteristics

 $V_{HH} = V_{H} = 15.0V, V_{M13} = V_{M24} = 1.0V, GND = 0.0V,$ 

 $V_{CC1}=V_{CC2}=5.0V (=V_{CC}), V_{L1}=-7.0V, V_{L2}=-10.0V, Ta=+25^{\circ}C$ 

	, ·L2	1010 1, 14 120 0				
Parameter	Symbol	Test conditions	min	typ	max	Unit
Quiescent supply current	I <sub>DDST</sub>	V <sub>I</sub> =GND, V <sub>CC</sub>			4	mA
Operating supply current	I <sub>DDDYN</sub>	V <sub>I</sub> =GND, V <sub>CC</sub>			11	mA
Power supply output pins	OV	<sub>DD</sub> , OV <sub>EE</sub>				
Positive voltage stabilization	V <sub>REG+</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>O</sub> =7mA	14.5	15.0	15.5	V
circuit output voltage						
Negative voltage stabilization	V <sub>REG-</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>O</sub> =-2mA	-10.5	-10.0	-9.5	V
circuit output voltage						
Input pins	IV1	, IV2, IV3, IV4, CH1, CH2, ISUB,	HD			
"H" level voltage	V <sub>IH</sub>		3.5		V <sub>CC</sub>	V
"L" level voltage	V <sub>IL</sub>		GND		1.5	V
Input leak current	I <sub>LI</sub>	V <sub>I</sub> =0 to 5V			±1	μΑ
Output pins 1 (Binary output	t) OV	2, OV4		1	1	1
Output voltage "M" level	V <sub>OM1</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OM1</sub> =-1mA	0.9		V <sub>M24</sub>	V
Output voltage "L" level	V <sub>OL1</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OL1</sub> =1mA	V <sub>L1</sub>		-6.9	V
Output on resistance "M" level	R <sub>ONM1</sub>	I <sub>OM1</sub> =-50mA			40	Ω
Output on resistance "L" level	R <sub>ONL1</sub>	I <sub>OL1</sub> =50mA			40	Ω
Output pins 2 (Tristate output	ut) OV	1, OV3				
Output voltage "H" level	V <sub>OH2</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OH2</sub> =-1mA	14.9		V <sub>H</sub>	V
Output voltage "M" level	V <sub>OM2</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OM2</sub> =-1mA	0.9		V <sub>M13</sub>	V
Output voltage "L" level	V <sub>OL2</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OL2</sub> =1mA	V <sub>L1</sub>		-6.9	V
Output on resistance "H" level	R <sub>ONH2</sub>	I <sub>OH2</sub> =-50mA			50	Ω
Output on resistance "M" level	R <sub>ONM2</sub>	I <sub>OM2</sub> =±50mA			40	Ω
Output on resistance "L" level	R <sub>ONL2</sub>	I <sub>OL2</sub> =50mA			40	Ω
Output pin 3 (SUB output)	OS	JB	-	1		
Output voltage "H" level	V <sub>OHH3</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OHH3</sub> =-1mA	14.9		V <sub>HH</sub>	V
Output voltage "L" level	V <sub>OL3</sub>	V <sub>I</sub> =GND, V <sub>CC</sub> , I <sub>OL3</sub> =1mA	V <sub>L2</sub>		-9.9	V
Output on resistance "H" level	R <sub>ONHH3</sub>	I <sub>ONHH3</sub> =-50mA			50	Ω
Output on resistance "L" level	R <sub>ONL3</sub>	I <sub>ONL3</sub> =50mA			40	Ω
		1				

#### (2) AC characteristics

 $V_{HH} = V_{H} = 15.0V, V_{M13} = V_{M24} = 1.0V, GND = 0.0V,$ 

 $V_{CC1}=V_{CC2}=5.0V (=V_{CC}), V_{L1}=-7.0V, V_{L2}=-10.0V, Ta=+25^{\circ}C$ 

Parameter	Symbol	Test conditions	min	typ	max	Unit
Output pins 1 (Binary outp	ut) OV	2, OV4				
Transmission delay	t <sub>PLM</sub>	No load		100	200	
	t <sub>PML</sub>	From "L" level to "M" level		100	200	ns
Rise time	t <sub>TLM</sub>			200	300	
Fall time	t <sub>TML</sub>			200	300	ns
Output pins 2 (Tristate out	out) OV	1, OV3				
Transmission delay	t <sub>PLM</sub>	No load		100	200	ns
	t <sub>PML</sub>	From "L" level to "M" level				
Transmission delay	t <sub>PMH</sub>	No load		200	400	
	t <sub>PHM</sub>	From "M" level to "H" level		200	400	ns
Rise time	t <sub>TLM</sub>			200	300	ns
Fall time	t <sub>TML</sub>			200	300	115
Rise time	t <sub>TMH</sub>			200	300	
Fall time	t <sub>THM</sub>			200	300	ns
Output pin 3 (SUB output)	OS	UB				
Transmission delay	t <sub>PLHH</sub>	No load		100	200	
	t <sub>PHHL</sub>	From "L" level to "H" level		100	200	ns
Rise time	t <sub>TLHH</sub>			200	200	
Fall time	t <sub>THHL</sub>			200	300	ns

# Timing Chart

1. Binary transfer pulses



#### Application Circuit Example



The booster circuit's electrolytic capacitors must have little impedance fluctuation at low temperatures.

Note \*1: These diodes must have a V<sub>F</sub> of 0.7 V. All other diodes, except the Zener diodes, must be Schottky barrier diodes (MA723).

# Package Dimensions (Unit: mm)

#### QFH048-P-0707



Note) The package of this product will be changed to lead-free type (QFH048-P-0707B). See the new package dimensions section later of this datasheet.

#### Usage Notes

#### External components

 This product requires eight Schottky barrier diodes and two Zener diodes. We recommend the following components.

Schottky barrier diodes:	MA723 or equivalents
Zener diodes:	MA1150-M, MA8150-M (for positive regulated voltage) or equivalents
	MA1100-M, MA8100-M (for negative regulated voltage) or equivalents

Ta=25°C

Component	Model number	Typical characteristics	Notes
Schottky barrier diodes	MA723	$I_F = 200 \text{mA}, V_F \le 0.55 \text{V}$	
	MA1150-M		for positive
Zener diodes	MA8150-M	$I_Z = 5mA, 14.6V \le V_Z \le 15.35V$	regulated voltage
Zener ulodes	MA1100-M		for negative
	MA8100-M	$I_Z = 5mA, 9.75V \le V_Z \le 10.25V$	regulated voltage

The MN3111H will not operate properly if the components do not satisfy the above specifications.

2. Always use the specified components for peripheral circuits so as to ensure that  $OV_{EE}$  and  $V_L$  do not reverse potentials when the power is turned off.



As the above sketch illustrates, allowing  $OV_{EE}$  to exceed  $V_{L1}$  and  $V_{L2}$  by more than 0.7 V produces the risk of applying a forward bias to the PN junction, turning on the parasitic transistor, and generating an overcurrent that produces latch-up.

If this phenomenon arises, increase the size of capacitor C7 or decrease the size of capacitor C13 to increase the  $OV_{EE}$  time constant.

(See the sample application circuit for the locations of C7 and C13.)

- New Package Dimensions (Unit: mm)
- QFH048-P-0707B (Lead-free package)



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